

# VALTRON® UltraLux™

## TEMPORARY BONDING WAX



## UltraLux™ LF Series

### Liquid Wax Adhesive for Temporary Mounting

VALTRON® UltraLux™ LF series liquid wax adhesive is designed for semiconductor and PV wafer substrates that are greater than two inches in diameter. UltraLux™ LF series liquid wax adhesive exhibits high bond strength, good temperature tolerance and low viscosity, which provides a reliable, thin layer of adhesive onto device wafer and wafer substrates.

#### UNIQUE FEATURES

- High Bond Strength at High Processing Speed
- High Softening Point and Melting Temperature
- Low Viscosity and Excellent Liquidity
- Ultra Tight TTV

#### INSTRUCTIONS FOR USE

Coating of VALTRON® UltraLux™ can be done by spin-coater or desired coating method. Solvent can be evaporated by baking (recommended temperature is 100°C-120°C). Mount the substrate onto desired substrate carrier plate. Demounting can be performed by dipping and soaking the adhered substrate into an IPA (isopropyl alcohol) bath. In order to accelerate the demounting process, a warmed IPA bath at 40°C-60°C is recommended. Cleaning the substrate can be done by using IPA or precision cleaning using VALTRON® SP2200 detergent.

#### PACKAGING

VALTRON® UltraLux™ is available in 1 L bottles.



#### TYPICAL PHYSICAL PROPERTIES

Appearance	Dark Brown
Melting Point	80-90°C
Specific Gravity	0.90
Shore D Hardness	68
Viscosity (cP @ 25°C)	< 100 cP
Lap Shear Strength (kg/cm <sup>2</sup> )	65.0 ± 10.0
Wax Concentration	40.0 ± 1%

